

H273-Z85-AAW1

High Density Server - 2U 4-Node DP 8-Bay NVMe/SATA



Features

- 2U 4-node rear access server system
- Dual AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 24 x DIMMs per node
- Dual ROM Architecture
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 4 x LP PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Application

HPC, HCI, Hybrid/Private Cloud Server

Specification

Dimensions	2U 4-Node - Rear access (W440 x H87.5 x D877 mm)	TPM	4 x TPM headers with SPI interface - Optional TPM2.0 kit: CTM010
Motherboard	MZ83-HD2	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor, cTDP up to 300W - At ambient 25°C, cTDP up to 400W with optional heatsink and air shroud	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
Socket	8 x LGA 6096 (Socket SP5)	OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
Chipset	System on Chip	System Fans	4 x 80x80x80mm (16,900rpm)
Memory	12-Channel DDR5 RDIMM, 96 x DIMMs [EPYC 9005] RDIMM: Up to 6000 MT/s [EPYC 9004] RDIMM: Up to 4800 MT/s	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
LAN	8 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Support NCSI function 4 x 10/100/1000 management LAN	Packaging Content	1 x H273-Z85-AAW1, 8 x CPU heatsinks 1 x Mini-DP to D-Sub cable, 1 x 3-Section Rail kit Packaging Dimensions: 1179 x 700 x 380 mm
Video	Integrated in ASPEED® AST2600 x 4 - 4 x Mini-DP	Part Numbers	Barebone package (cTDP 400W): 6NH273Z85DR000ACW1* Barebone package (EPYC 9005/9004): 6NH273Z85DR000ABW1* Barebone package (EPYC 9004): 6NH273Z85DR000AAW1* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - M.2 expansion card - CMTP192: 9CMTP192NR-00* - CPU heatsink (400W, 25°C ambient, Front): 25ST1-253212-A0R - Air shroud (400W, 25°C ambient): 25HA8-H27330-G1R
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA/SAS-4 *SAS card is required to support SAS drives. Optional internal M.2: 4 x M.2 (2280/22110)		
Expansion Slots	4 x LP PCIe Gen5 x16 slots		
Rear I/O	8 x USB 3.2 Gen1, 4 x Mini-DP, 8 x RJ45, 4 x MLAN		
Backplane Board	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s		



Learn more at <https://www.GIGABYTE.com/enterprise>

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